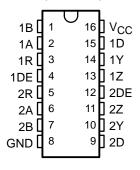
SN75ALS1177, SN75ALS1178 DUAL DIFFERENTIAL DRIVERS AND RECEIVERS

SLLS154B - MARCH 1993 - REVISED FEBRUARY 2001

- Meet or Exceed Standards TIA/EIA-422-B and TIA/EIA-485-A
- Designed for Multipoint Bus Transmission on Long Bus Lines in Noisy Environments
- Low Supply-Current Requirement 50 mA Max
- Driver Positive- and Negative-Current Limiting
- Driver Common-Mode Output Voltage Range of -7 V to 12 V
- Thermal Shutdown Protection
- Driver 3-State Outputs Active-High Enable
- Receiver Common-Mode Input Voltage Range of -12 V to 12 V
- Receiver Input Sensitivity . . . ±200 mV
- Receiver Hysteresis . . . 50 mV Typ
- Receiver High Input Impedance . . . 12 kΩ Min
- Receiver 3-State Outputs Active-Low Enable for SN75ALS1177 Only
- Operate From Single 5-V Supply

SN75ALS1177 ... N OR NS PACKAGE (TOP VIEW) 1B l 16 V_{CC} 15 1D 1A 🛮 2 1R **∏** 3 14 1 1Y RE [4 13 T 1Z 12 DE 2R 🛮 5 2А П 11 **[**] 27 2B 🛮 7 10 2Y GND 8 9 🛮 2D

SN75ALS1178...N OR NS PACKAGE (TOP VIEW)



description

The SN75ALS1177 and SN75ALS1178 dual differential drivers and receivers are integrated circuits designed for bidirectional data communication on multipoint bus transmission lines. They are designed for balanced transmission lines and meet standards TIA/EIA-422-B and TIA/EIA-485-A.

The SN75ALS1177 combines dual 3-state differential line drivers and dual 3-state differential input line receivers, both of which operate from a single 5-V power supply. The drivers and receivers have active-high and active-low enables, respectively, which can be externally connected together to function as direction control. The SN75ALS1178 drivers each have an individual active-high enable. Fail-safe design ensures that when the receiver inputs are open, the receiver outputs are always high.

The SN75ALS1177 and SN75ALS1178 are characterized for operation from 0°C to 70°C.

AVAILABLE OPTIONS

	PACKAGED DEVICES				
TA	PLASTIC DIP (N)	PLASTIC SMALL OUTLINE (NS)			
	SN75ALS1177N	SN75ALS1177NSR			
0°C to 70°C					

The NS package is only available taped and reeled. Add the suffix R to the device type (e.g., SN75ALS1177NSR).



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



Function Tables

SN75ALS1177, SN75ALS1178 (each driver)

INPUT	ENABLE	OUTI	PUTS
D	DE	Y	Z
Н	Н	Н	L
L	Н	L	Н
Х	L	Z	Z

SN75ALS1177 (each receiver)

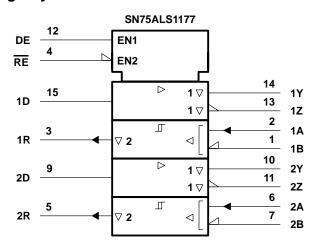
DIFFERENTIAL A–B	ENABLE RE	OUTPUT Y
$V_{ID} \ge 0.2 V$	L	Н
$-0.2 \text{ V} < \text{V}_{\text{ID}} < 0.2 \text{ V}$	L	?
V _{ID} ≤ -0.2 V	L	L
X	Н	Z
Open	L	Н

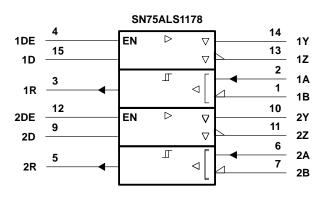
SN75ALS1178 (each receiver)

DIFFERENTIAL A-B	OUTPUT Y
V _{ID} ≥ 0.2 V	Н
-0.2 V < V _{ID} < 0.2 V	?
V _{ID} ≤ -0.2 V	L
Open	Н

H = High level, L = Low level, ?=Indeterminate, X = Irrelevant, Z = High impedance (off)

logic symbol†

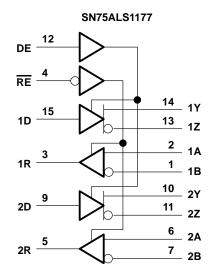


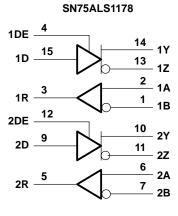


[†] These symbols are in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

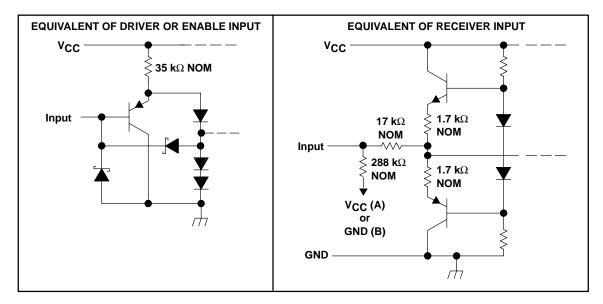


logic diagram (positive logic)



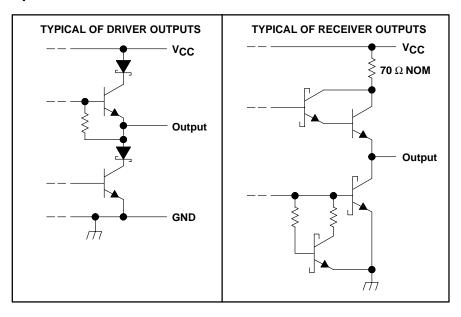


equivalent schematics



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schematics of outputs



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC} (see Note 1)	7 V
Input voltage, V _I (DE, RE, and D inputs)	7 V
Output voltage range, V _O (driver)	
Input voltage range, receiver	–14 V to 14 V
Receiver differential-input voltage range (see Note 2)	–14 V to 14 V
Receiver low-level output current	50 mA
Package thermal impedance, θ _{JA} (see Note 3): N package	67°C/W
NS package	64°C/W
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C
Storage temperature range, T _{stq}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential input voltage, are with respect to the network ground terminal.
 - 2. Differential input voltage is measured at the noninverting terminal with respect to the inverting terminal.
 - 3. The package thermal impedance is calculated in accordance with JESD 51-7.



SN75ALS1177, SN75ALS1178 DUAL DIFFERENTIAL DRIVERS AND RECEIVERS

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recommended operating conditions

			MIN	NOM	MAX	UNIT
VCC	Supply voltage		4.75	5	5.25	V
VID	Differential input voltage	Receiver			±12	V
Voc	Common-mode output voltage	Driver	_7 [†]		12	V
VIC	Common-mode input voltage	Receiver			±12	V
VIH	High-level input voltage	DE, RE, D	2			V
V _{IL}	Low-level input voltage	DE, RE, D			0.8	V
10	High lovel output current	Driver			-60	mA
ІОН	High-level output current	Receiver			-400	μΑ
la.	Laureland autout annuat	Driver			60	mA
lor	Low-level output current	Receiver			8	IIIA
TA	T _A Operating free-air temperature					°C

[†] The algebraic convention, where the less positive (more negative) limit is designated as minimum, is used in this data sheet for common-mode output and threshold voltage level only.

DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS			MIN	TYP [†]	MAX	UNIT
VIK	Input clamp voltage	I _I = -18 mA					-1.5	V
Vон	High-level output voltage	V _{IH} = 2 V,	$V_{IL} = 0.8 V$,	$I_{OH} = -33 \text{ mA}$		3.3		V
V_{OL}	Low-level output voltage	V _{IH} = 2 V,	$V_{IL} = 0.8 V$,	$I_{OL} = 33 \text{ mA}$		1.1		V
VOD1	Differential output voltage	IO = 0			1.5		6	V
IVOD2I	Differential output voltage	V _{CC} = 5 V,	R _L = 100 Ω,	See Figure 1	1/2 V _{OD1} or 2‡			V
	· -	$R_L = 54 \Omega$,	See Figure 1		1.5	2.5	5	
VOD3	Differential output voltage	See Note 4			1.5		5	V
Δ V _{OD}	Change in magnitude of differential output voltage (see Note 5)	$R_L = 54 \Omega$ or 1	100 Ω,	See Figure 1			±0.2	V
Voc	Common-mode output voltage	$R_L = 54 \Omega$ or 1	100 Ω,	See Figure 1	-1§		3	V
Δ VOC	Change in magnitude of common-mode output voltage (see Note 5)	$R_L = 54 \Omega$ or 1	100 Ω,	See Figure 1			±0.2	V
l _{O(OFF)}	Output current with power off	$V_{CC} = 0$,	$V_{O} = -7 \text{ V to } 1$	2 V			±100	μΑ
loz	High-impedance-state output current	$V_O = -7 \text{ V to } ^{-1}$	12 V				±100	μΑ
lιΗ	High-level input current	V _{IH} = 2.7 V					100	μΑ
I _{IL}	Low-level input current	V _{IL} = 0.4 V					-100	μΑ
		$V_0 = -7 \text{ V}$					-250	
loo	Short-circuit output current	$V_{O} = V_{CC}$					250	mA
los	Short-chedit output current	V _O = 12 V					250	IIIA
		V _O = 0 V	_				150	
Icc	Supply current (total package)	No load	Outputs enable	ed		35	50	mA
iCC	Supply culterit (total package)	Outputs disabled				20	50	IIIA

NOTES: 4. See TIA/EIA-485-A Figure 3.5, test termination measurement 2.

switching characteristics at V_{CC} = 5 V, T_A = 25°C (unless otherwise noted)

	PARAMETER	TEST	CONDITIONS	MIN	TYP	MAX	UNIT
tPLH	Propagation delay time, high- to low-level output	$R_L = 60 \Omega, C_{L1} = 0$ See Figure 3	$R_L = 60 \Omega$, $C_{L1} = C_{L2} = 100 pF$, See Figure 3		15	22	ns
tPHL	Propagation delay time, low- to high-level output	$R_L = 60 \Omega, C_{L1} = 0$ See Figure 3	C _{L2} = 100 pF,	9	15	22	ns
t _{sk}	Output-to-output skew	$R_L = 60 \Omega$, $C_{L1} = 0$ See Figure 3	$R_L = 60 \Omega$, $C_{L1} = C_{L2} = 100 pF$, See Figure 3		2	8	ns
tPZH	Output enable time to high level	C _L = 100 pF,	See Figure 4	30	35	50	ns
tPZL	Output enable time to low level	C _L = 100 pF,	See Figure 5	5	15	25	ns
t _{PHZ}	Output disable time from high level	C _L = 15 pF,	See Figure 4	7	15	30	ns
tPLZ	Output disable time from low level	C _L = 15 pF,	See Figure 5	7	15	30	ns



[†] All typical values are at $V_{CC} = 5$ V and $T_A = 25$ °C. ‡ The minimum V_{OD2} with a 100- Ω load is either 1/2 V_{OD1} or 2 V, whichever is greater.

[§] The algebraic convention, where the less positive (more negative) limit is designated as minimum, is used in this data sheet for common-mode output and threshold voltage levels only.

^{5.} $\Delta |V_{OD}|$ and $\Delta |V_{OC}|$ are the changes in magnitude of V_{OD} and V_{OC} , respectively, that occur when the input is changed from a high level to a low level.

RECEIVER SECTION

electrical characteristics over recommended ranges of common-mode input voltage, supply voltage, and operating free-air temperature (unless otherwise noted)

	PARAMETER		TEST CO	NDITIONS	MIN	TYP†	MAX	UNIT
V _{IT+}	Positive-going input threshold voltage		$V_0 = 2.7 V$,	$I_{O} = -0.4 \text{ mA}$			0.2	V
V _{IT} _	Negative-going input threshold voltage		$V_0 = 0.5 V$,	I _O = 8 mA	-0.2‡			V
V _{hys}	Input hysteresis voltage (V _{IT+} – V _{IT-})					50		mV
VIK	Enable input clamp voltage	SN75ALS1177	I _I = -18 mA				-1.5	V
V _{OH} High-level output voltage		V_{ID} = 200 mV, I_{OH} = -400 μ A, See Figure 2		2.7			V	
V _{OL} Low-level output voltage		V _{ID} = 200 mV, I _{OL} = 8 mA, See Figure 2				0.45	V	
loz	High-impedance-state output current	SN75ALS1177	$V_0 = 0.4 \text{ V to } 2.4 \text{ V}$	/			±20	μΑ
1.	Line input surrent (see Note 6)		V _I = 12 V				1	A
'1	Line input current (see Note 6)		Other input at 0 V	V _I = -7 V			-0.8	mA
ΠH	High-level input current, RE	SN75ALS1177	V _{IH} = 2.7 V				20	μΑ
Ι _{ΙL}	Low-level input current, RE	SN75ALS1177	V _{IL} = 0.4 V				-100	μΑ
rį	Input resistance				12			kΩ
los	Short-circuit output current		V _O = 0 V,	See Note 7	-15		-85	mA
Icc	Supply current (total package)		No load,	Outputs enabled		35	50	mA

NOTES: 6. Refer to TIA/EIA-422-B, TIA/EIA-423-A, and TIA/EIA-485-A for exact conditions.

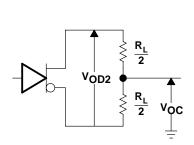
switching characteristics at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$ (unless otherwise noted)

PARAMETER			TEST C	ONDITIONS	MIN	TYP	MAX	UNIT
tPLH	Propagation delay time, low- to high-lev	el output	C _L = 15 pF,	See Figure 6	15	25	37	ns
tPHL	Propagation delay time, high- to low-level output		C _L = 15 pF,	See Figure 6	15	25	37	ns
^t PZH	Output enable time to high level	SN75ALS1177	$C_L = 100 pF$,	See Figure 7	10	20	30	ns
t _{PZL}	Output enable time to low level	SN75ALS1177	$C_L = 100 pF$,	See Figure 7	10	20	30	ns
tPHZ	Output disable time from high level	SN75ALS1177	C _L = 15 pF,	See Figure 7	3.5	12	16	ns
tPLZ	Output disable time from low level	SN75ALS1177	C _L = 15 pF,	See Figure 7	5	12	16	ns

[†] All typical values are at V_{CC} = 5 V and T_A = 25°C. ‡ The algebraic convention, where the less positive (more negative) limit is designated as minimum, is used in this data sheet for common-mode output and threshold voltage levels only.

^{7.} Not more than one output should be shorted at a time.

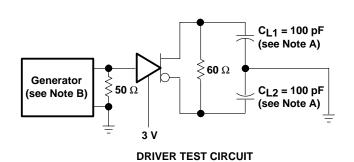
PARAMETER MEASUREMENT INFORMATION

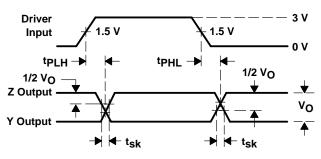


IOH VOL

Figure 1. Driver Test Circuit, VOD and VOC

Figure 2. Receiver Test Circuit, VOH and VOL

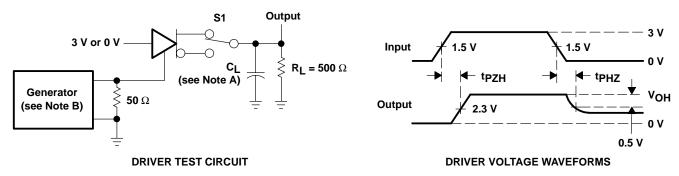




DRIVER VOLTAGE WAVEFORMS

- NOTES: A. C_L includes probe and jig capacitance.
 - B. The pulse generator has the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_{\Gamma} \leq$ 10 ns, $t_{f} \leq$ 10 ns.

Figure 3. Driver Propagation Delay Times

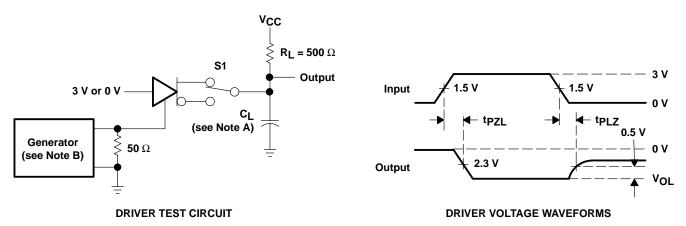


- NOTES: A. C_I includes probe and jig capacitance.
 - B. The pulse generator has the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_{\Gamma} \leq$ 10 ns, $t_{\Gamma} \leq$ 10 ns.

Figure 4. Driver Enable and Disable Times



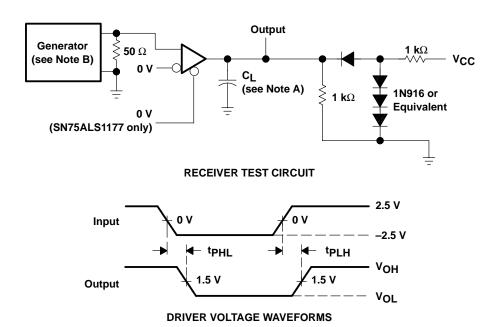
PARAMETER MEASUREMENT INFORMATION



NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_f \leq$ 10 ns. $t_f \leq$ 10 ns.

Figure 5. Driver Enable and Disable Times

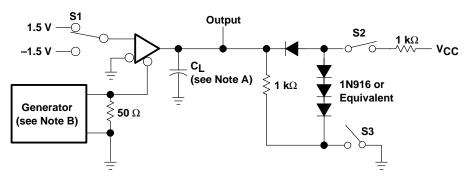


NOTES: A. C_L includes probe and jig capacitance.

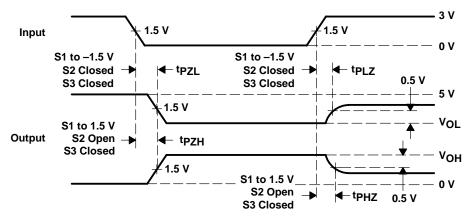
B. The pulse generator has the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_{\Gamma} \leq$ 10 ns, $t_{f} \leq$ 10 ns.

Figure 6. Receiver Propagation Delay Times

PARAMETER MEASUREMENT INFORMATION



RECEIVER TEST CIRCUIT



RECEIVER VOLTAGE WAVEFORMS

NOTES: A. C_L includes probe and jig capacitance.

B. The pulse generator has the following characteristics: PRR \leq 1 MHz, 50% duty cycle, $t_{\Gamma} \leq$ 10 ns, $t_{\Gamma} \leq$ 10 ns.

Figure 7. Receiver Output Enable and Disable Times





i.com 4-Jun-2007

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN75ALS1177N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75ALS1177NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75ALS1177NSLE	OBSOLETE	SO	NS	16		TBD	Call TI	Call TI
SN75ALS1177NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS1177NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS1177NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS1178N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75ALS1178NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75ALS1178NSLE	OBSOLETE	SO	NS	16		TBD	Call TI	Call TI
SN75ALS1178NSR	ACTIVE	so	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75ALS1178NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION





Α	0	Dimension designed to accommodate the component width
В	0	Dimension designed to accommodate the component length
		Dimension designed to accommodate the component thickness
٧	٧	Overall width of the carrier tape
ГР	1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing			Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75ALS1177NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
SN75ALS1178NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1





*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75ALS1177NSR	SO	NS	16	2000	346.0	346.0	33.0
SN75ALS1178NSR	SO	NS	16	2000	346.0	346.0	33.0

MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



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